




APPLICABLE STANDARD					
RATING	VOLTAGE	AC 150 V	CURRENT	1 A	
	OPERATING TEMPERATURE RANGE	-35°C TO +85 °C (NOTES 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C (NOTE3)	
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTES 2)	STORAGE HUMIDITY RANGE	20 % TO 70 % (NOTE3)	
	APPLICABLE CONNECTOR	DF13-*S-1.25C	APPLICABLE CONTACT	DF13-2630SCF, DF13-3032SCF	
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.			X	X
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).		30 mΩ MAX.	X	-
INSULATION RESISTANCE	100 V DC.		500 MΩ MIN.	X	-
VOLTAGE PROOF	500 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	X	-
MECHANICAL CHARACTERISTICS					
MECHANICAL OPERATION	30 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			X	-
ENVIRONMENTAL CHARACTERISTICS					
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → 5 TO 35 → +85 → 5 TO 35 °C TIME 30 → 5 MAX → 30 → 5 MAX min UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			X	-
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING «REFLOW AREA» MAX250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec «PREHEATING AREA» 170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	-
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230±3°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSSED.	X	-
REMARKS					
NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT					
NOTE2:NO CONDENSING					
NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION.					
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
					
Unless otherwise specified, refer to JIS C 5402.			APPROVED	TY.OMA	06.10.23
			CHECKED	HK.UMEHARA	06.10.19
			DESIGNED	TS.KUMAZAWA	06.10.18
			DRAWN	AK.MIURA	06.10.18
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.	ELC4-083664-03	
	SPECIFICATION SHEET		PART NO.	DF13-*P-1.25V (20)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL536	 1/1